PCN Num	ber:		20240328001.1				<b>PCN Date:</b> March 28, 2024				h 28, 2024		
Title:	Qua	lification	of RFA	of RFAB using qualified Process Technology, Die Revision,				sion,					
				additional Assembly site/BOM options for select devices									
Customer	Con	tact:	Change Management Tear					Dep			Qual	ity Services	
Proposed	1 <sup>st</sup> S	hip Dat	e: Ju	e: June 26, 2024			Sample requests A accepted until:			April	27, 2024*		
*Sample	requ	ests rec	eived	after	April 27	, 202	24 will	not b	e si	uppo	orted		
Change T	ype:				_								
Assen	nbly S	Site			Design					Wat	<sup>f</sup> er Bu	Imp Material	
		Process		Data Sheet								Imp Process	
		<b>Materials</b>					<sup>-</sup> change			-		b Site	
		Specific			Test Sit							b Material	
🛛 Packii	ng/Sh	ipping/l	abeling	g 🗌	Test Pro				$\boxtimes$	Wat	<sup>f</sup> er Fa	b Process	
					PCN I	Deta	ails						
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	nal W											ation facility as he devices	
	Cı	irrent F	ab Sit	e				Addi	tion	al Fa	Fab Site ss Wafer Diameter		
Current	Fab	Proc	ess		afer		ditional		Pro	cess	;		
Site				Dia	meter	Fa	ab Site					Diameter	
SFAB		JI			) mm								
	SFAB O				) mm		RFAB		LE	BC7		300 mm	
SFAB The die wa		IMPC6			) mm								
Construction Group 1 E				Fro	m			То					
Wire diam	n/type	e		0.96m	nil Cu	0.80mil C		Cu					
Group 2 E	Devic	e		ASE	CU.			1LA				FMX	
Wire diam	a /tvp	2	0.80r	-	-				<u></u>			).80mil Cu	
Mount co				0mil Au, 1.0mil Cu EY1000063			0.96mil Cu 4147858					4147858	
				EN2000506			4147838					4211880	
	Group 3 Device												
Wire diam	1/tvp	9		1.0m			MLA 0.80mil Cu						
Mount co				EY100			4147858						
Mold compound				EN200			4211471						
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Texas Instruments

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AM26C31 SLLS103P – DECEMBER 1990 – REVISED MARCH 2024

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INSTRUMENTS		SLLS085C - JANUARY 1977	SN75158 - REVISED MARCH 2024
hanges from Revision B	(May 1995) to Revision C	(March 2024)	Page
-		nd cross-references throughout the doc	<u> </u>
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26			
TEXAS INSTRUMENTS			SN75ALS191
		SLLS032C – DECEMBER 1987	
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Product Folder	Current Datasheet Number	New Datasheet Number	Link to full datasheet
AM26C31	SLLS1030	SLLS103P	http://www.ti.com/product/AM26C31
AM26LS31	SLLS114L	SLLS114M	http://www.ti.com/product/AM26LS31
MC3487	SLLS098C	SLLS098D	http://www.ti.com/product/MC3486
SN75158	SLLS085B	SLLS085C	http://www.ti.com/product/SN75158
SN75ALS192	SLLS007D	SLLS007E	http://www.ti.com/product/SN75ALS192
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Texas Instruments Incorporated

TI Information - Selective Disclosure PCN# 20240328001.1

SN75ALS191	SLLS032B	SLLS032C	http://www.ti.com/product/SN75ALS191
SN75ALS194	SLLS009D	SLLS009D	http://www.ti.com/product/SN75ALS194
uA9638C	SLLS112C	SLLS112D	http://www.ti.com/product/uA9638C
-			

Qual details are provided in the Qual Data Section.

## **Reason for Change:**

These changes are part of our multiyear plan to transition products from our 150-millimeter factories to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

# Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

# **Impact on Environmental Ratings:**

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474				
🛛 🛛 No Change	🛛 🛛 No Change	🛛 🖂 No Change	🛛 No Change				
Changes to product identification resulting from this PCN:							

## Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City	
SH-BIP-1	SHE	USA	Sherman	
RFAB	RFB	USA	Richardson	

# **Die Rev:**

Current	New
Die Rev [2P]	Die Rev [2P]
A, B, E,-	-

# **Assembly Site Information:**

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
ASESH	ASH	CHN	Shanghai
MLA	MLA	MYS	Kuala Lumpur
FMX	MEX	MEX	Aguascalientes

Sample product shipping label (not actual product label)

MADE IN: Malaysia 2DC: 2Q: MSL'2 /260C/1 YEAR MSL 1 /235C/UNLIM OPT: ITEM:   DI + 5A /   \TA	03/29/04 39		LA 33512 3517 9:USA
LBL: 5A (L)TO	:1750	 (LOL) OGO. ONL	0:USA 0: MYS

Group 1 Product Affected:						
AM26C31CNSR	AM26LS31CN	SN75ALS191DR	SN75ALS194NSR			

AM26C31IDBR	AM26LS31CN-E	SN75ALS191P	UA9638CDR				
AM26C31IDBRE4	AM26LS31CNSR	SN75ALS191PE4	UA9638CDRG4				
AM26C31IDR	MC3487DR	SN75ALS191PSR	UA9638CP				
AM26C31IN	SN75158DR	SN75ALS192DR	UA9638CPE4				
AM26C31INE4	SN75158P	SN75ALS192NSR					
AM26C31INSR	SN75158PSR	SN75ALS194DR					
Group 2 Product Affe	Group 2 Product Affected:						
AM26LS31CDR							
Group 3 Product Affected:							
AM26C31IPWR	AM26C31IPWR						

For alternate parts with similar or improved performance, please visit the product page on  $\underline{\text{TI.com}}$ 

## **Qualification Results**

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	#	Test Name	Condition	Duration	Qual Device: <u>AM26LS31CDR</u>	QBS Reference: <u>TPS2543QRTETQ1</u>	QBS Reference: <u>TL494IDR</u>	QBS Reference: <u>MC33063ADR</u>	QBS Reference: <u>AM26LV31EIDR</u>
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0	3/231/0	-
UHAST	A3	Autoclave	130C/85%RH	96 Hours	-	3/231/0	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	3/231/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	-	3/231/0	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	-	3/231/0	-
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	3/135/0	-	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	3/231/0	-	1/77/0	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/2400/0	-	2/1600/0	-
WBS	C1	Ball Shear	76 balls, 3 units min	Wires	-	-	-	-	1/76/0
WBP	C2	Bond Pull	76 Wires, 3 units min	Wires	-	-	-	-	1/76/0
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-	-	-

PD	C4	Physical Dimensions	Cpk>1.67	-	-	3/30/0	-	-	-
ESD	E2	ESD CDM	-	250 Volts	1/3/0	1/3/0	-	-	1/3/0
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	1/3/0	-	-	1/3/0
LU	E4	Latch-Up	Per JESD78	-	1/3/0	1/6/0	-	-	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	1/30/0	1/30/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	3/90/0	-	-	-
FTY	E6	Final Test Yield	-	-	1/1/0	-	-	-	-

QBS: Qual By Similarity

Qual Device AM26LS31CDR is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

• The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

• The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

TI Qualification ID: R-CHG-2301-005

#### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	#	Test Name	Condition	Duration	Qual Device: SN75ALS194DR	Qual Device: SN75ALS192DR	Qual Device: MC3487DR	Qual Device: AM26C31IDR	Qual Device: <u>UA9638CDR</u>	Qual Device: SN75ALS191DR	Qual Device: <u>SN75158DR</u>	QBS Reference (Process, Product): <u>SN3257QDYYRQ1</u>	QBS Reference (Package): TPS7B4256QDRQ1	QBS Reference (Product): AM26LS31CDR
HAST	AZ	Biased HAST	130C/85%RH	96 Hours				-					3/240/0	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours				-					3/240/0	-
тс	A4	Temperature Cycle	-65C/150C	500 Cycles							-		3/240/0	
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-		-	-		-	-	3/150/0	-
HTOL	B1	Life Test	150C	300 Hours				-			-	3/231/0		
ELFR	B2	Early Life Failure Rate	150C	24 Hours	-	-	-	-		-	-	3/2400/0	-	-
WBS	C1	Ball Shear	76 balls, 3 units min	Wires	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0			-
WBP	C2	Bond Pull	76 Wires, 3 units min	Wires	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0			-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-				-	-		-	-	1/30/0	-
SD	СЗ	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-		-	-	-	-	-	1/30/0	-
ESD	E2	ESD CDM	-	1000 Volts	1/3/0	-	-	-	1/3/0	1/3/0	1/3/0	-	-	-
ESD	E2	ESD HBM		2000 Volts	1/3/0	1/3/0	1/3/0	-			1/3/0			1/3/0
LU	E4	Latch-Up	Per JESD78	-	1/3/0	1/3/0	1/3/0	-	-	-	1/3/0		-	1/3/0
Туре	#	Test Name	Condition	Duration	Qual Device: SN75ALS194DR	Qual Device: SN75ALS192DR	Qual Device: MC3487DR	Qual Device: AM26C31IDR	Qual Device: UA9638CDR	Qual Device: SN75ALS191DR	Qual Device: SN75158DR	QBS Reference (Process, Product): SN22570DVVP01	QBS Reference (Package): TPS7B4256QDRQ1	QBS Reference (Product): AM26LS31CDR

					SN/SALS194DR	SN/SALS192DR	MC3487DR	AM26C31IDR	UA9638CDR	SN/SALS191DR	SN75158DR	SN3257QDYYRQ1	TPS7B4256QDRQ1	AM26LS31CD
CHAP	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	1/30/0	1/30/0	1/30/0	1/30/0	1/30/0	-		1/30/0

QBS: Qual By Similarity

Qual Device SN75ALS194DR is gualified at MSL1 260C

Qual Device SN75ALS192DR is qualified at MSL1 260C Qual Device SN75ALS192DR is qualified at MSL1 260C Qual Device MC3487DR is qualified at MSL1 260C Qual Device AM26C31DR is qualified at MSL1 260C

Oual Device UA9638CDR is gualified at MSL2 260C

Qual Device SN75ALS191DR is qualified at MSL1 260C

Qual Device SN75158DR is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
 The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
 The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
 The following are equivalent TEmp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2205-051

## **Qualification Results**

## Data Displayed as: Number of lots / Total sample size / Total failed

Туре	#	Test Name	Condition	Duration	Qual Device: <u>AM26C31IPWR</u>	QBS Reference (Process, Package): <u>SN3257QPWRQ1</u>	QBS Reference (Process): <u>TPS2543QRTETQ1</u>	QBS Reference (Product): AM26LS31CDR
HAST	A2	Biased HAST	130C	96 Hours	-	3/231/0	-	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	1/77/0	3/231/0	-	-
тс	A4	Temperature Cycle	-40C/85C	1000 Cycles	1/77/0	-	-	-
тс	A4	Temperature Cycle	-55/150C	1000 Cycles	-	3/231/0	-	-
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	3/135/0	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	3/231/0	-
HTOL	B1	Life Test	150C	300 Hours	-	3/231/0	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	3/2400/0	-
WBS	C1	Ball Shear	76 balls, 3 units min	Wires	1/76/0	-	-	-
WBP	C2	Bond Pull	76 Wires, 3 units min	Wires	1/76/0	-	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-	-
Туре	#	Test Name	Condition	Duration	Qual Device: <u>AM26C31IPWR</u>	QBS Reference (Process, Package): <u>SN3257QPWRQ1</u>	QBS Reference (Process): <u>TPS2543QRTETQ1</u>	QBS Reference (Product): <u>AM26LS31CDR</u>
SD	СЗ	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-	-
ESD	E2	ESD CDM	-	1000 Volts	1/3/0	-	-	-
ESD	E2	ESD HBM	-	1000 Volts	-	-	-	1/3/0
LU	E4	Latch-Up	Per JESD78	-	-	-	-	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	1/30/0

• QBS: Qual By Similarity

Qual Device AM26C31IPWR is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

• The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

• The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2205-049

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	*	Test Name	Condition	Duration	Qual Device: AM26C31CNSR	Qual Device: <u>SN75ALS194NSR</u>	Qual Device: <u>SN75ALS192NSR</u>	Qual Device: AM26C31INSR	Qual Device: AM26C31IDBR	Qual Device: SN75ALS191PSR	Qual Device: <u>SN75158PSR</u>	Qual Device: AM26LS31CNSR	QBS Reference (Process, Product): <u>SN3257QDYYRQ1</u>	QBS Reference (Package): TL092CPS	QBS Reference (Package): SN75ALS1177NS	QBS Reference (Product): AM26LS31CDR
UHAST	A3	Autoclave	121C/15psig	96 Hours		-	-	-	-	-	-	-	-	3/230/0	3/231/0	-
тс	A4	Temperature Cycle	-65C/150C	500 Cycles				-						3/231/0	3/231/0	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours										3/231/0		
HTOL	81	Life Test	150C	300 Hours				-		-	-		3/231/0	-		-
ELFR	B2	Early Life Failure Rate	150C	24 Hours				-					3/2400/0	-		-
WBS	C1	Ball Shear	76 balls, 3 units min	Wires	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0		-		-
WBP	C2	Bond Pull	76 Wires, 3 units min	Wires	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0		-		-
ESD	E2	ESD CDM		1000 Volts		1/3/0		-	1/3/0	1/3/0	1/3/0	1/3/0		-		1/3/0
ESD	E2	ESD HBM		2000 Volts		-		-						-		1/3/0
LU	E4	Latch-Up	Per JESD78	•				-	-	-	-		-	-		1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters			1/30/0	1/30/0	1/30/0	1/30/0	1/30/0	1/30/0	1/30/0	-	-		1/30/0
FTY	E6	Final Test Yield	-	•				-	-	-	-		-	-		1/1/0

QBS: Qual By Similarity
 Qual Device AM26C31CNSR is qualified at MSL1 260C
 Qual Device SN75ALS194NSR is qualified at MSL1 260C
 Qual Device SN75ALS194NSR is qualified at MSL1 260C
 Qual Device AM26C3110SR is qualified at MSL1 260C
 Qual Device AM26C3110SR is qualified at MSL1 260C
 Qual Device SN75ALS191PSR is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

Preconducting was performed or nucleave, of nucleave (As), reinperature cycle, international stock, and PT32, as applicable
The following are equivalent PTOL options based on an activation energy of 0.7eV : 125C/L4Nurs; 140C/480 Hours; 100C/480 Hours; and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/L4 Hours; and 170C/420 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/L4 Hours; and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2206-026

## Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	#	Test Name	Condition	Duration	Qual Device: <u>AM26LS31CN</u>	Qual Device: <u>UA9638CP</u>	Qual Device: <u>SN75ALS191P</u>	Qual Device: <u>SN75158P</u>	Qual Device: AM26C31IN	Qual Device: <u>AM26LS31CN-</u> E	QBS Reference (Process, Product): <u>SN3257QDYYRQ1</u>	QBS Reference (Package): <u>SN74HC595N</u>	QBS Reference (Package): <u>TLC339IN</u>	QBS Reference (Product): AM26LS31CDR
UHAST	A3	Autoclave	121C/15psig	96 Hours				-		-	-	3/231/0	3/231/0	-
тс	A4	Temperature Cycle	-65C/150C	500 Cycles		-		-		-	-	3/231/0	3/231/0	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	-	-	-	-	-	3/231/0	3/231/0	-
HTOL	В1	Life Test	150C	300 Hours			-	-		-	3/231/0	-		-
ELFR	B2	Early Life Failure Rate	150C	24 Hours			-	-			3/2400/0	-	-	-
WBS	C1	Ball Shear	76 balls, 3 units min	Wires	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	-	-	-	-	-
WBP	C2	Bond Pull	76 Wires, 3 units min	Wires	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0		-	-	-	-
SD	СЗ	PB-Free Solderability	8 Hours Steam Age	-		-		-			-	3/66/0	3/66/0	-
ESD	E2	ESD CDM		1000 Volts	1/3/0	-	1/3/0	-	1/1/0	-	-	-		-
ESD	E2	ESD HBM		1000 Volts				-			-	-		1/3/0
ESD	E2	ESD HBM		2000 Volts		1/3/0	1/3/0	-		-	-			
LU	E4	Latch-Up	Per JESD78	-	-	1/3/0	1/3/0	-	-	-	-	-	-	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	1/30/0	1/30/0	-	-	-	-	-	1/30/0

QBS: Qual By Similarity

Qual Device AM26LS31CN is qualified at NOT CLASSIFIED NOT CLASSIFIED
 Qual Device UA9638CP is qualified at NOT CLASSIFIED NOT CLASSIFIED
 Qual Device SN75ALS191P is qualified at NOT CLASSIFIED NOT CLASSIFIED

Qual Device SN75158P is qualified at NOT CLASSIFIED NOT CLASSIFIED
 Qual Device AM26C31IN is qualified at NOT CLASSIFIED NOT CLASSIFIED

Qual Device AM26LS31CN-E is qualified at NOT CLASSIFIED NOT CLASSIFIED

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
 The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2205-050

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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